ABSTRACT

In one aspect, provided is a cleaning agent composition for wafer processing that has high ability to remove a wafer processing adhesive.

An aspect of the present disclosure relates to a cleaning agent composition for wafer processing to remove a wafer processing adhesive remaining on a wafer. The cleaning agent composition contains a nitrogen-containing aprotic polar solvent having 2 or more and 10 or less carbon atoms (component A) and an organic amine (component B). The component A is a nitrile compound. A Hansen solubility parameter value of a mixed solvent of the component A and the component B is 20.0 or more and 26.0 or less.